

In the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims

1. (currently amended) A process for removing a thermal barrier ceramic coating from a cooling hole of a component comprising:

drilling cooling holes into the component after a bond coat application and prior to a thermal barrier ceramic coating application;

coating the component, including the cooling holes, with the thermal barrier ceramic coating;

directing an air jet at a side of the component, opposing a surface having the thermal barrier ceramic coating, the jet containing a non-abrasive spherical particulate media and sucking the media from a nozzle of the jet at a low pressure wherein said low pressure is insufficient for the media to damage a substrate but said low pressure is sufficient for the media to remove the thermal barrier ceramic coating from the cooling hole; and

wherein a bond coating is interposed between the thermal barrier ceramic coating and the substrate; and

wherein the pressure of the air jet is from about 20 to 100 PSIG;

2. (renewed)

3. (cancelled)

4. (currently amended) The process of claim 1 wherein the spherical media particles have a diameter of from about 0.002 to 0.010 inches.

5. (previously presented) The process of claim 4 wherein the media is glass beads.